

MM54HC242/MM74HC242 Inverting Quad TRI-STATE® Transceiver MM54HC243/MM74HC243 Quad TRI-STATE Transceiver

General Description

These TRI-STATE bidirectional inverting and non-inverting buffers utilize advanced silicon-gate CMOS technology and are intended for two-way asynchronous communication between data buses. They have high drive current outputs which enable high speed operation when driving large bus capacitances. These circuits possess the low power dissipation and high noise immunity associated with CMOS circuits, but speeds comparable to low power Schottky TTL circuits. They can also drive 15 LS-TTL loads.

The MM54HC243/MM74HC243 is a non-inverting buffer and the MM54HC242/MM74HC242 is an inverting buffer. Each device has one active high enable (GBA), and one active low enable ($\overline{\text{GAB}}$). GBA enables the A outputs and

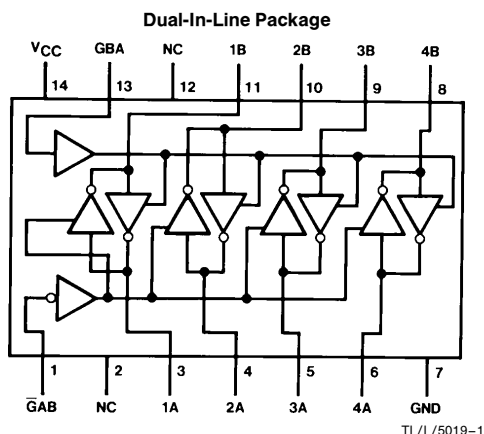
$\overline{\text{GAB}}$ enables the B outputs. This device does not have Schmitt trigger inputs.

All inputs are protected from damage due to static discharge by diodes to V_{CC} and ground.

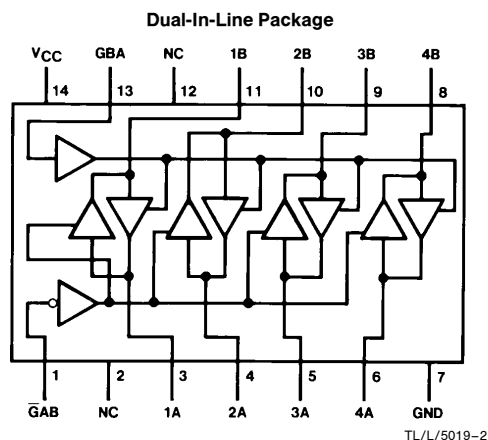
Features

- Typical propagation delay: 12 ns
- TRI-STATE outputs
- Two way asynchronous communication
- High output current: 6 mA (74HC)
- Wide power supply range: 2–6V
- Low quiescent supply current: 80 μA (74HC)

Connection Diagrams



Top View
Order Number MM54HC242 or MM74HC242



Top View
Order Number MM54HC243 or MM74HC243

Truth Tables

'HC242

Control Inputs		Data Port Status	
$\overline{\text{GAB}}$	GBA	A	B
H	H	OUTPUT	Input
L	H	Isolated	Isolated
H	L	Isolated	Isolated
L	L	Input	OUTPUT

'HC243

Control Inputs		Data Port Status	
$\overline{\text{GAB}}$	GBA	A	B
H	H	OUTPUT	Input
L	H	Isolated	Isolated
H	L	Isolated	Isolated
L	L	Input	OUTPUT

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Absolute Maximum Ratings (Notes 1 & 2)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/Distributors for availability and specifications.

Supply Voltage (V_{CC})	−0.5 to +7.0V
DC Input Voltage (V_{IN})	−1.5 to $V_{CC} + 1.5V$
DC Output Voltage (V_{OUT})	−0.5 to $V_{CC} + 0.5V$
Clamp Diode Current (I_{IK}, I_{OK})	±20 mA
DC Output Current, per pin (I_{OUT})	±35 mA
DC V_{CC} or GND Current, per pin (I_{CC})	±70 mA
Storage Temperature Range (T_{STG})	−65°C to +150°C
Power Dissipation (P_D)	
(Note 3)	600 mW
S.O. Package only	500 mW
Lead Temp. (T_L) (Soldering 10 seconds)	260°C

Operating Conditions

	Min	Max	Units
Supply Voltage (V_{CC})	2	6	V
DC Input or Output Voltage (V_{IN}, V_{OUT})	0	V_{CC}	V
Operating Temp. Range (T_A)			
MM74HC	−40	+85	°C
MM54HC	−55	+125	°C
Input Rise or Fall Times (t_r, t_f)			
$V_{CC} = 2.0V$		1000	ns
$V_{CC} = 4.5V$		500	ns
$V_{CC} = 6.0V$		400	ns

DC Electrical Characteristics (Note 4)

Symbol	Parameter	Conditions	V _{CC}	T _A = 25°C		74HC T _A = −40 to 85°C	54HC T _A = −55 to 125°C	Units
				Typ	Guaranteed Limits			
V _{IH}	Minimum High Level Input Voltage		2.0V		1.5	1.5	1.5	V
			4.5V		3.15	3.15	3.15	V
			6.0V		4.2	4.2	4.2	V
V _{IL}	Maximum Low Level Input Voltage**		2.0V		0.5	0.5	0.5	V
			4.5V		1.35	1.35	1.35	V
			6.0V		1.8	1.8	1.8	V
V _{OH}	Minimum High Level Output Voltage	V _{IN} = V _{IH} or V _{IL} I _{OUT} ≤ 20 μA	2.0V	2.0	1.9	1.9	1.9	V
			4.5V	4.5	4.4	4.4	4.4	V
			6.0V	6.0	5.9	5.9	5.9	V
		V _{IN} = V _{IH} or V _{IL} I _{OUT} ≤ 6.0 mA I _{OUT} ≤ 7.8 mA	4.5V	4.2	3.98	3.84	3.7	V
			6.0V	5.7	5.48	5.34	5.2	V
V _{OL}	Maximum Low Level Output Voltage	V _{IN} = V _{IH} or V _{IL} I _{OUT} ≤ 20 μA	2.0V	0	0.1	0.1	0.1	V
			4.5V	0	0.1	0.1	0.1	V
			6.0V	0	0.1	0.1	0.1	V
		V _{IN} = V _{IH} or V _{IL} I _{OUT} ≤ 6.0 mA I _{OUT} ≤ 7.8 mA	4.5V	0.2	0.26	0.33	0.4	V
			6.0V	0.2	0.26	0.33	0.4	V
I _{IN}	Maximum Input Current	V _{IN} = V _{CC} or GND	6.0V		± 0.1	± 1.0	± 1.0	μA
I _{OZ}	Maximum TRI-STATE Output Leakage Current	V _{OUT} = V _{CC} or GND G _{AB} = V _{IH} , G _{BA} = V _{IL}	6.0V		± 0.5	± 5.0	± 10	μA
I _{CC}	Maximum Quiescent Supply Current	V _{IN} = V _{CC} or GND I _{OUT} = 0 μA	6.0V		8.0	80	160	μA

Note 1: Absolute Maximum Ratings are those values beyond which damage to the device may occur.

Note 2: Unless otherwise specified all voltages are referenced to ground.

Note 3: Power Dissipation temperature derating — plastic "N" package: −12 mW/°C from 65°C to 85°C; ceramic "J" package: −12 mW/°C from 100°C to 125°C.

Note 4: For a power supply of 5V ±10% the worst case output voltages (V_{OH} , and V_{OL}) occur for HC at 4.5V. Thus the 4.5V values should be used when designing with this supply. Worst case V_{IH} and V_{IL} occur at $V_{CC} = 5.5V$ and 4.5V respectively. (The V_{IH} value at 5.5V is 3.85V.) The worst case leakage current (I_{IN} , I_{CC} , and I_{OZ}) occur for CMOS at the higher voltage and so the 6.0V values should be used.

** V_{IL} limits are currently tested at 20% of V_{CC} . The above V_{IL} specification (30% of V_{CC}) will be implemented no later than Q1, CY'89.

AC Electrical Characteristics (MM54HC242/MM74HC242)

$V_{CC} = 5V$, $T_A = 25^\circ C$, $t_r = t_f = 6\text{ ns}$

Symbol	Parameter	Conditions	Typ	Guaranteed Limit	Units
t_{PHL} , t_{PLH}	Maximum Propagation Delay	$C_L = 45\text{ pF}$	12	18	ns
t_{PZH} , t_{PZL}	Maximum Output Enable Time to Active Output	$R_L = 1\text{ k}\Omega$ $C_L = 45\text{ pF}$	17	28	ns
t_{PHZ} , t_{PHL}	Maximum Output Disable Time from Active Output	$R_L = 1\text{ k}\Omega$ $C_L = 5\text{ pF}$	15	25	ns

AC Electrical Characteristics (MM54HC242/MM74HC242, MM54HC243/MM74HC243)

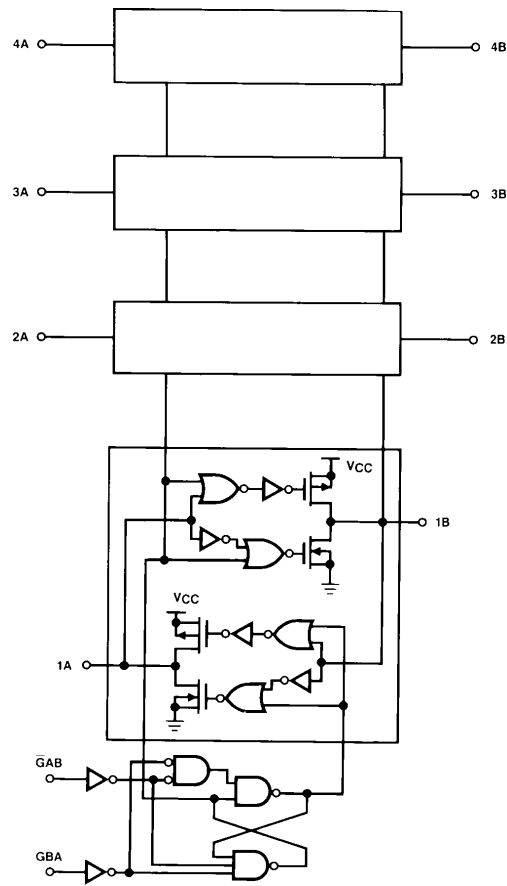
$V_{CC} = 2.0V$ to $6.0V$, $C_L = 50\text{ pF}$, $t_r = t_f = 6\text{ ns}$ (unless otherwise specified)

Symbol	Parameter	Conditions	V _{CC}	T _A = 25°C		74HC T _A = −40 to 85°C		54HC T _A = −55 to 125°C		Units
				Typ	Guaranteed Limits					
t _{PHL} , t _{PLH}	Maximum Propagation Delay	C _L = 50 pF	2.0V	55	100	126	149	ns		
		C _L = 150 pF	2.0V	80	150	190	224	ns		
		C _L = 50 pF	4.5V	12	20	25	30	ns		
		C _L = 150 pF	4.5V	22	30	38	45	ns		
		C _L = 50 pF	6.0V	11	17	21	25	ns		
		C _L = 150 pF	6.0V	18	26	32	38	ns		
t _{PZH} , t _{PZL}	Maximum Output Enable Time to Active Output	R _L = 1 kΩ	2.0V	75	150	189	224	ns		
		C _L = 50 pF	2.0V	100	200	252	298	ns		
		C _L = 50 pF	4.5V	15	30	38	45	ns		
		C _L = 150 pF	4.5V	30	40	50	60	ns		
		C _L = 50 pF	6.0V	13	26	32	38	ns		
		C _L = 150 pF	6.0V	17	34	43	51	ns		
t _{PHZ} , t _{PLZ}	Maximum Output Disable Time from Active Output	R _L = 1 kΩ	2.0V	75	150	189	224	ns		
		C _L = 50 pF	4.5V	15	30	38	45	ns		
		C _L = 50 pF	6.0V	13	26	32	38	ns		
t _{TLH} , t _{THL}	Maximum Output Rise and Fall Time		2.0V		60	75	90	ns		
			4.5V		12	15	18	ns		
			6.0V		10	13	15	ns		
C _{PD}	Power Dissipation Capacitance (Note 5)	(per buffer) Outputs Disabled Outputs Enabled		12 50				pF pF		
C _{IN}	Maximum Input Capacitance			5	10	10	10	pF		
C _{OUT}	Maximum Output Capacitance			10	20	20	20	pF		

Note 5: C_{PD} determines the no load dynamic power consumption, $P_D = C_{PD} V_{CC}^2 f + I_{CC} V_{CC}$, and the no load dynamic current consumption, $I_S = C_{PD} V_{CC} f + I_{CC}$.

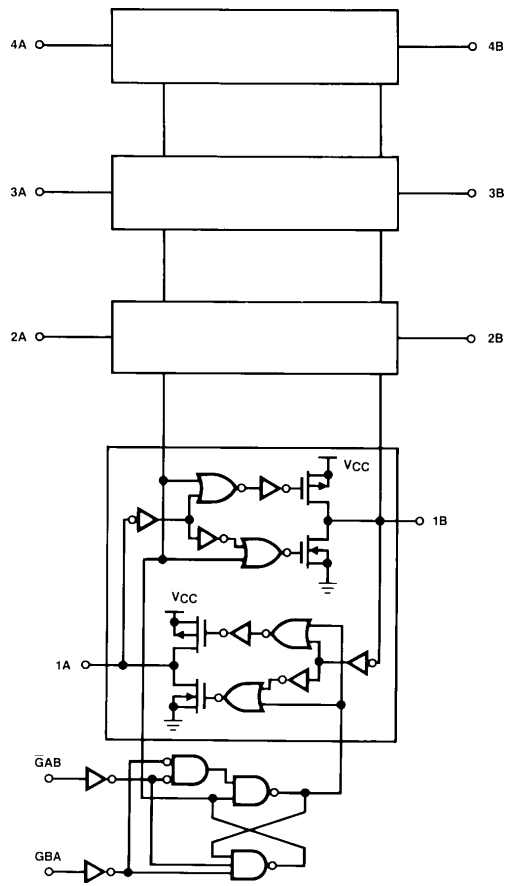
Logic Diagrams

MM54HC242/MM74HC242



TL/L/5019-3

MM54HC243/MM74HC243



TL/L/5019-4

